

ABSTRACT

It is to improve the storage stability of a sealant, to retain the flowability of the sealant when sealing, and to achieve an effective curing rate of the sealant by heating to be applicable as a sealant for delicate semiconductors.

It is an epoxy resin composition for sealing a semiconductor, comprising the following component (A) and component (B).

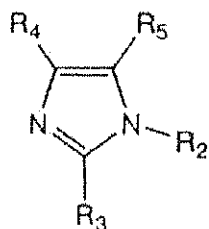
(A) an epoxy resin,

(B) a clathrate complex comprising

(b1) an aromatic carboxylic acid compound, and

(b2) at least one imidazole compound represented by formula

(II)



(II)

(wherein R_2 represents a hydrogen atom, etc.; R_3 to R_5 represent a hydrogen atom, etc.).